

### Description

The DFS600HF17I3C2 is a Half Bridge SiC MOSFET Power Module. It integrates high performance SiC MOSFET chips designed for the applications such as Motor drives and Renewable energy.



### Features

- Blocking voltage 1700V
- $R_{DS(on)} = 3.4m\Omega$
- Low thermal resistance with Si<sub>3</sub>N<sub>4</sub> AMB
- 175°C maximum junction temperature
- Low Inductive Design
- Thermistor inside
- Pressfit terminal
- Copper base size: 79mmx62mm

### Applications

- Motor Drives
- Servo Drives
- UPS Systems
- Smart-Grid/Grid-Tied Distributed Generation

### Circuit diagram

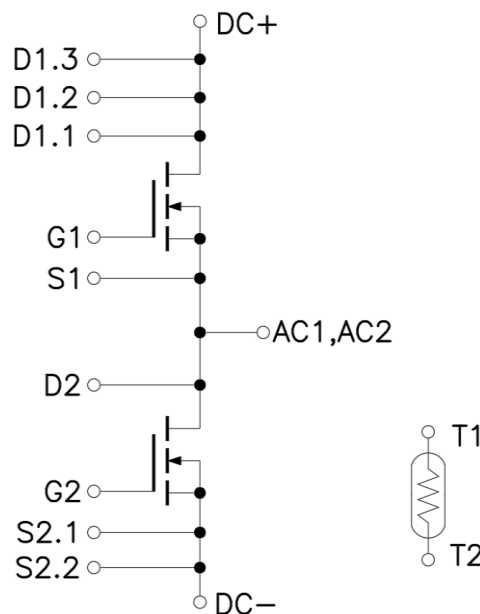


Figure 1. Out drawing & circuit diagram for DFS600HF17I3C2

### Pin Configuration and Marking Information

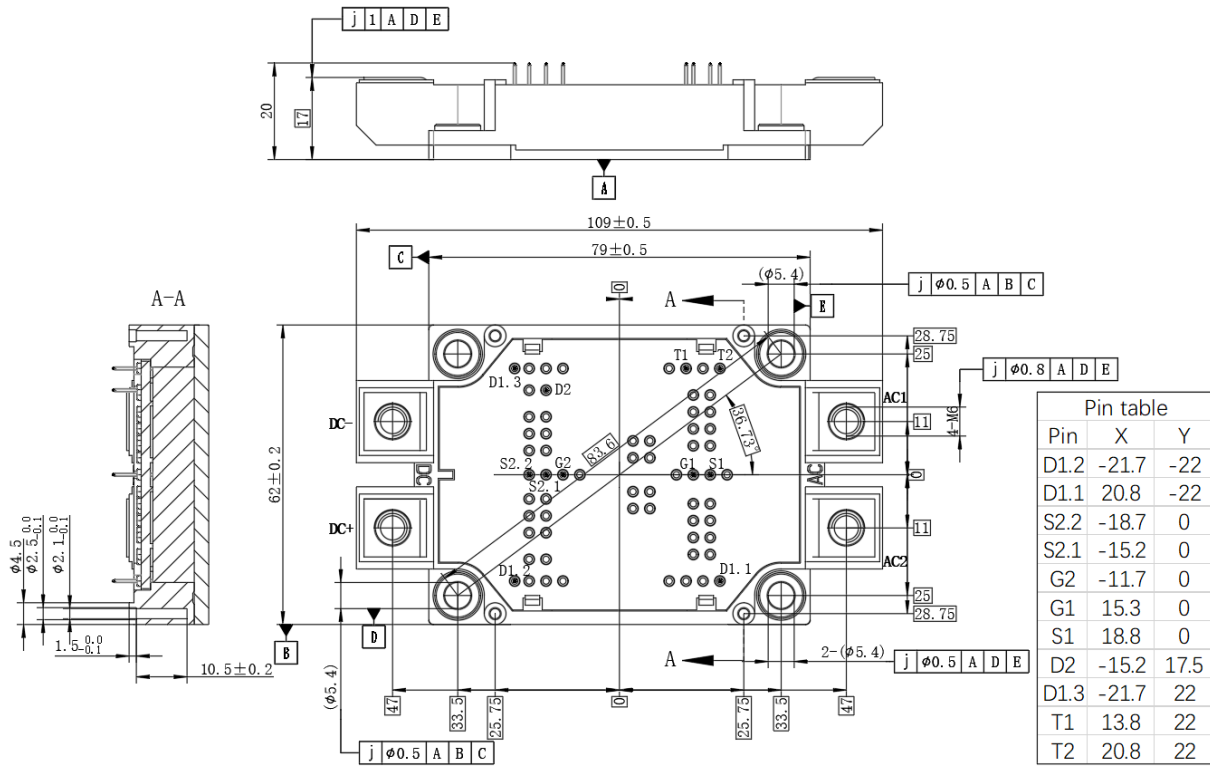


Figure 2. Pin configuration

### Module

| Parameter                              | Conditions                                   | Value      | Unit |
|--|--|------------|------|
| Isolation Voltage                      | RMS, f =50Hz, t =1min                        | 4          | KV   |
| Material of module baseplate           | -  | Cu         | -    |
| Creepage distance                      | terminal to heatsink<br>terminal to terminal | 14.5<br>10 | mm   |
| Clearance                              | terminal to heatsink<br>terminal to terminal | 12.5<br>10 | mm   |
| CTI                                    | -  | 600        | -    |
| Module lead resistance, terminals–chip | T <sub>c</sub> =25°C                         | 0.5        | mΩ   |
| Mounting torque for module mounting    | M5, M6                                       | 3 to 6     | Nm   |
| Weight                                 | -  | 250        | g    |

### Maximum Ratings ( $T_j = 25^\circ\text{C}$ unless otherwise specified)

| Symbol         | Parameter                                   | Conditions  | Ratings    | Unit             |
|----------------|---|---|------------|------------------|
| $V_{DSS}$      | Drain-Source Voltage                        | G-S Short   | 1700       | V                |
| $V_{GSS}$      | Gate-Source Voltage (+)                     | D-S Short   | 20         | V                |
| $V_{GSS}$      | Gate-Source Voltage (-)                     | D-S Short   | -10        | V                |
| $V_{GSSSurge}$ | G-S Voltage( $t_{surge} < 300\text{nsec}$ ) | D-S Short, Note1  | -10 to 20  | V                |
| $I_{DS}$       | DC Continuous Drain Current                 | $T_C = 25^\circ\text{C}$ , $V_{GS} = 15\text{V}$                            | 585        | A                |
| $I_{DS}$       | DC Continuous Drain Current                 | $T_C = 80^\circ\text{C}$ , $V_{GS} = 15\text{V}$                            | 465        | A                |
| $I_{SD}$       | Source (Body diode) Current                 | $T_C = 25^\circ\text{C}$ , with ON signal                                   | 585        | A                |
| $I_{SD}$       | Source (Body diode) Current                 | $T_C = 80^\circ\text{C}$ , with ON signal                                   | 465        | A                |
| $I_{DSM}$      | Pulse Forward Current                       | $T_C = 25^\circ\text{C}$ , Pulse width = 1ms, $V_{GS} = 15\text{V}$ , Note2 | 1200       | A                |
| $P_{tot}$      | Total Power Dissipation                     | $T_C = 25^\circ\text{C}$  | 2630       | W                |
| $T_{jmax}$     | Max Junction Temperature                    | -   | 175        | $^\circ\text{C}$ |
| $T_{jop}$      | Operating junction Temperature              | -   | -40 to 150 | $^\circ\text{C}$ |
| $T_{stg}$      | Storage Temperature                         | -   | -40 to 125 | $^\circ\text{C}$ |

Note1: Recommended Operating Value, -4V/+15V, -5V/+15V

Note2: Pulse width limited by maximum junction temperature

### NTC characteristics

| Symbol       | Parameter              | Condition  | Value |      |      | Unit             |
|--------------|------------------------|--|-------|------|------|------------------|
|              |                        |  | Min.  | Typ. | Max. |                  |
| $R_{25}$     | Resistance             | $T_C = 25^\circ\text{C}$                                       | -     | 5    | -    | $\text{k}\Omega$ |
| $\Delta R/R$ | Deviation of $R_{100}$ | $T_C = 100^\circ\text{C}$ , $R_{100} = 493\Omega$              | 5     | -    | 5    | %                |
| $P_{25}$     | Power dissipation      | $T_C = 25^\circ\text{C}$                                       | -     | -    | 20   | mW               |
| $B_{25/50}$  | B-value                | $R_2 = R_{25} \exp [B_{25/50}(1/T_2 - 1/(298,15 \text{ K}))]$  | -     | 3375 | -    | K                |
| $B_{25/80}$  | B-value                | $R_2 = R_{25} \exp [B_{25/80}(1/T_2 - 1/(298,15 \text{ K}))]$  | -     | 3411 | -    | K                |
| $B_{25/100}$ | B-value                | $R_2 = R_{25} \exp [B_{25/100}(1/T_2 - 1/(298,15 \text{ K}))]$ | -     | 3433 | -    | K                |

### MOSFET Electrical characteristics (T<sub>j</sub> = 25°C unless otherwise specified, chip)

| Symbol                        | Item                            | Condition  | Value                  |       |      | Unit |    |
|-------------------------------|---------------------------------|--|------------------------|-------|------|------|----|
|                               |                                 |  | Min.                   | Typ.  | Max  |      |    |
| V <sub>(BR)DSS</sub>          | Drain-Source Breakdown Voltage  | V <sub>GS</sub> = 0V, I <sub>D</sub> = 160μA   | 1700                   | -     | -    | V    |    |
| I <sub>DSS</sub>              | Zero gate voltage drain Current | V <sub>DS</sub> = 1700V, V <sub>GS</sub> = 0V  | -                      | 4     | 160  | μA   |    |
| V <sub>GS(th)</sub>           | Gate-source threshold Voltage   | I <sub>D</sub> = 240mA<br>V <sub>DS</sub> = V <sub>GS</sub>  | T <sub>j</sub> = 25°C  | 1.8   | 2.70 | -    | V  |
|                               |                                 |  | T <sub>j</sub> = 175°C | -     | 1.90 | -    | V  |
| I <sub>GSS</sub>              | Gate-Source Leakage Current     | V <sub>GS</sub> = 15V, V <sub>DS</sub> = 0V, T <sub>j</sub> = 25°C   | -                      | -     | 1200 | nA   |    |
| R <sub>DS(on)</sub><br>(Chip) | Static drain-source             | I <sub>D</sub> = 600A<br>V <sub>GS</sub> = 15V   | T <sub>j</sub> = 25°C  | -     | 3.4  | 5.2  | mΩ |
|                               | On-state resistance             |  | T <sub>j</sub> = 175°C | -     | 7.7  | -    | mΩ |
| V <sub>DS(on)</sub><br>(Chip) | Static drain-source             | I <sub>D</sub> = 600A<br>V <sub>GS</sub> = 15V   | T <sub>j</sub> = 25°C  | -     | 2.04 | 3.12 | V  |
|                               | On-state Voltage                |  | T <sub>j</sub> = 175°C | -     | 4.62 | -    | V  |
| C <sub>iss</sub>              | Input Capacitance               | V <sub>D</sub> = 1000V, V <sub>GS</sub> = 0V<br>f = 1MHz, V <sub>ac</sub> = 25mV   | -                      | 45.7  | -    | nF   |    |
| C <sub>oss</sub>              | Output Capacitance              |  | -                      | 1.23  | -    | nF   |    |
| C <sub>rss</sub>              | Reverse transfer Capacitance    |  | -                      | 0.22  | -    | nF   |    |
| Q <sub>G</sub>                | Total gate charge               | V <sub>DD</sub> = 1000V, I <sub>D</sub> = 450A, V <sub>GS</sub> = -5/+15V  | -                      | 1536  | -    | nC   |    |
| R <sub>Gint</sub>             | Internal Gate Resistance        | T <sub>j</sub> = 25°C  | -                      | 0.32  | -    | Ω    |    |
| t <sub>d(on)</sub>            | Turn-on delay time              | V <sub>DD</sub> = 900V<br>I <sub>D</sub> = 600A<br>V <sub>GS</sub> = +15/-4V<br>R <sub>G(on)</sub> = 0.5Ω<br>R <sub>G(off)</sub> = 0.5Ω<br>Inductive load<br>switching operation | T <sub>j</sub> = 25°C  | -     | 73   | -    | ns |
|                               |                                 |  | T <sub>j</sub> = 150°C | -     | 66   | -    |    |
| t <sub>r</sub>                | Rise time                       |  | T <sub>j</sub> = 25°C  | -     | 50   | -    | ns |
|                               |                                 |  | T <sub>j</sub> = 150°C | -     | 47   | -    |    |
| t <sub>d(off)</sub>           | Turn-off delay time             |  | T <sub>j</sub> = 25°C  | -     | 179  | -    | ns |
|                               |                                 |  | T <sub>j</sub> = 150°C | -     | 216  | -    |    |
| t <sub>f</sub>                | Fall time                       |  | T <sub>j</sub> = 25°C  | -     | 43   | -    | ns |
|                               |                                 |  | T <sub>j</sub> = 150°C | -     | 46   | -    |    |
| E <sub>on</sub>               | Turn-on power dissipation       |  | T <sub>j</sub> = 25°C  | -     | 22.2 | -    | mJ |
|                               |                                 |  | T <sub>j</sub> = 150°C | -     | 26.3 | -    |    |
| E <sub>off</sub>              | Turn-off power dissipation      | T <sub>j</sub> = 25°C  | -                      | 27.5  | -    | mJ   |    |
|                               |                                 | T <sub>j</sub> = 150°C   | -                      | 30.2  | -    |      |    |
| R <sub>th(j-c)</sub>          | FET Thermal Resistance          | Junction to Case   | -                      | 0.057 | -    | K/W  |    |
| R <sub>th(c-f)</sub>          | Contact thermal Resistance      | With thermal conductive grease, Note4  | -                      | 0.015 | -    | K/W  |    |

Note4: Assumes Thermal Conductivity of grease is 0.9W/m · K and thickness is 50μm.

### Body Diode Electrical characteristics (T<sub>j</sub>=25°C unless otherwise specified, chip)

| Symbol          | Item                              | Condition  | Value                  |      |       | Unit |    |
|-----------------|-----------------------------------|--|------------------------|------|-------|------|----|
|                 |                                   |  | Min.                   | Typ. | Max.  |      |    |
| V <sub>SD</sub> | Body Diode Forward Voltage        | V <sub>GS</sub> = -4V<br>I <sub>SD</sub> = 360A                              | T <sub>j</sub> = 25°C  | -    | 4.8   | -    | V  |
|                 |                                   |  | T <sub>j</sub> = 150°C | -    | 4.5   | -    |    |
| T <sub>rr</sub> | Reverse recovery time             | V <sub>RR</sub> = 900V, I <sub>D</sub> = 600A<br>MOSFET side:                | T <sub>j</sub> = 25°C  | -    | 57    | -    | ns |
|                 |                                   |  | T <sub>j</sub> = 150°C | -    | 81    | -    |    |
| Q <sub>rr</sub> | Reverse recovery charge           | V <sub>GS</sub> = +15/-4V<br>R <sub>G(on)</sub> = R <sub>G(off)</sub> = 0.5Ω | T <sub>j</sub> = 25°C  | -    | 7.31  | -    | uC |
|                 |                                   |  | T <sub>j</sub> = 150°C | -    | 23.26 | -    |    |
| E <sub>rr</sub> | Diode switching power dissipation | Inductive load<br>switching operation  | T <sub>j</sub> = 25°C  | -    | 3.84  | -    | mJ |
|                 |                                   |  | T <sub>j</sub> = 150°C | -    | 15.39 | -    |    |

### Test Conditions

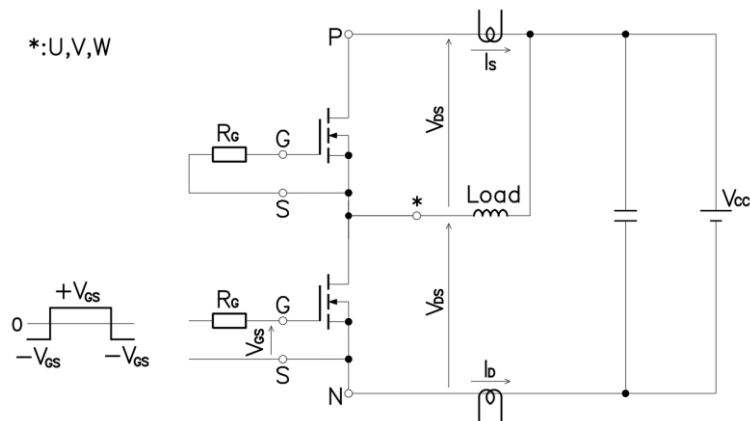


Figure 3. Switching time measure circuit

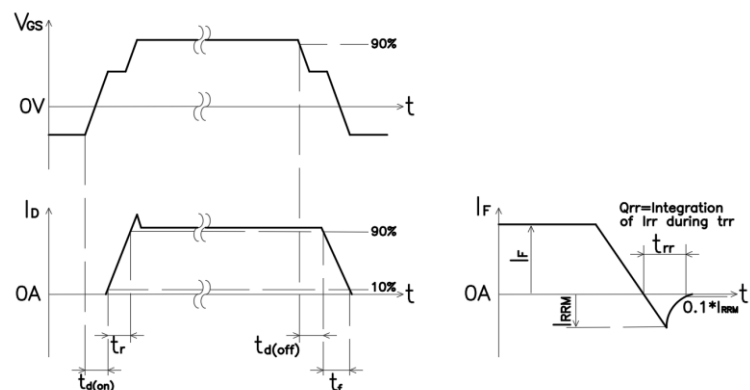


Figure 4. Switching time definition

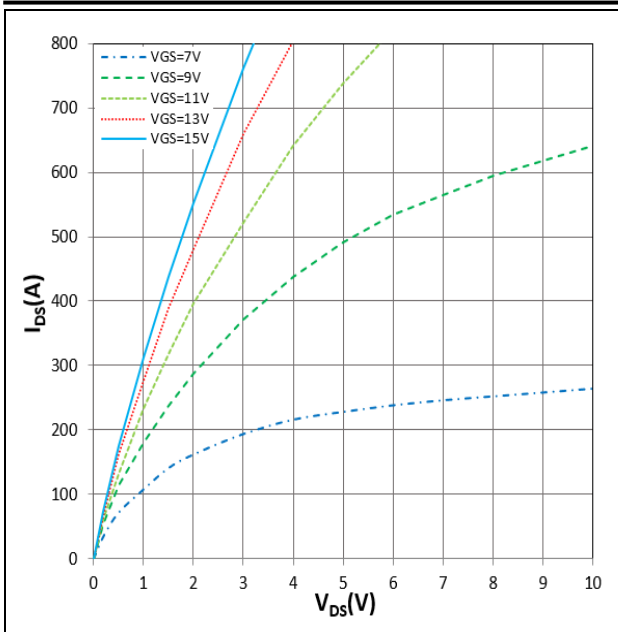


Figure 5.  $I_{DS}$  vs  $V_{DS}$   
 $T_j = 25^\circ\text{C}$ ,  $V_{GS}$  parameter

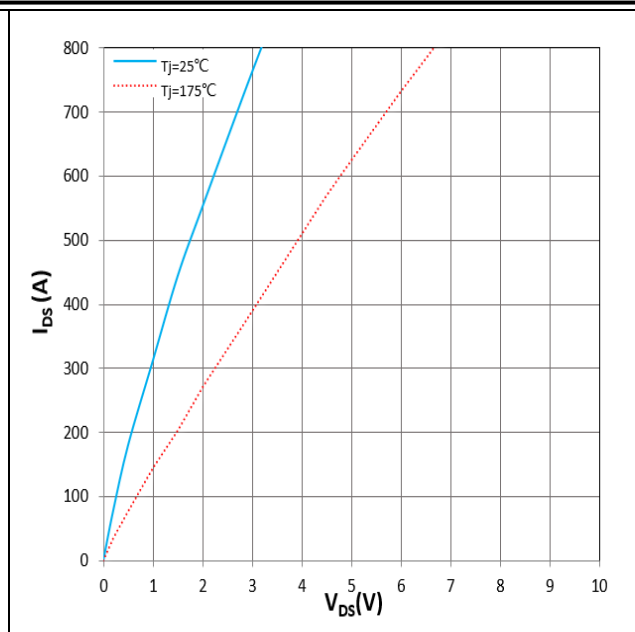


Figure 6.  $I_{DS}$  vs  $V_{DS}$   
 $V_{GS} = 15\text{V}$ ,  $T_j$  parameter

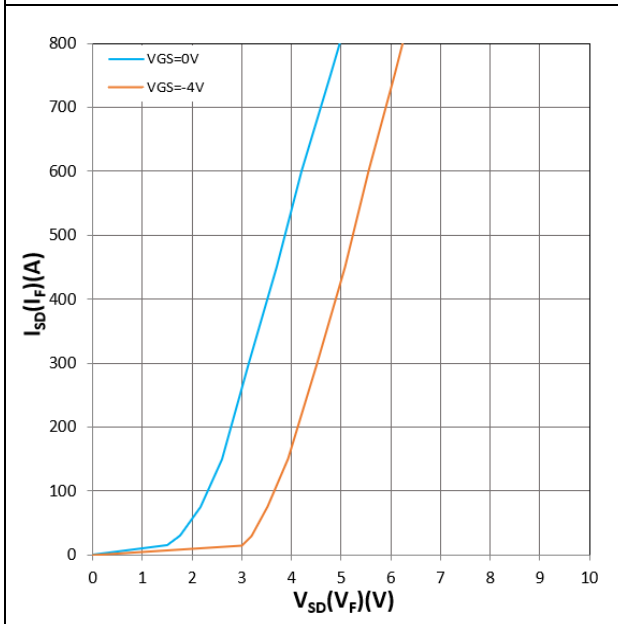


Figure 7.  $I_{SD}(I_F)$  vs  $V_{SD}(V_F)$   
 $T_j = 25^\circ\text{C}$ ,  $V_{GS}$  parameter

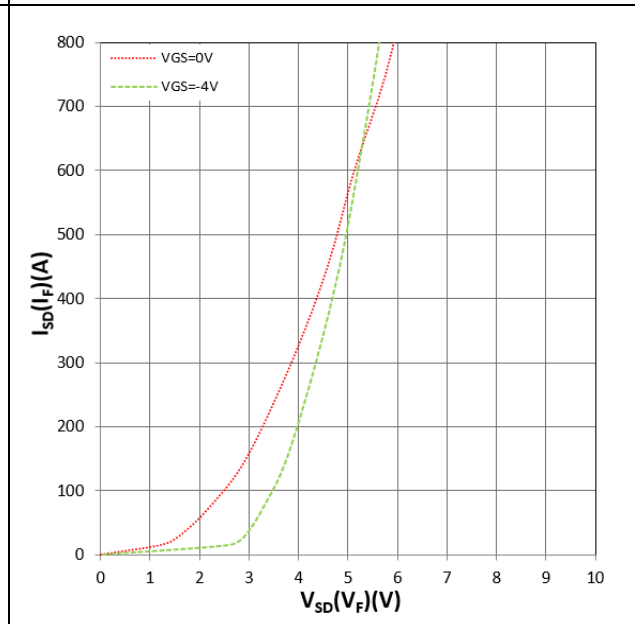


Figure 8.  $I_{SD}(I_F)$  vs  $V_{SD}(V_F)$   
 $T_j = 175^\circ\text{C}$ ,  $V_{GS}$  parameter

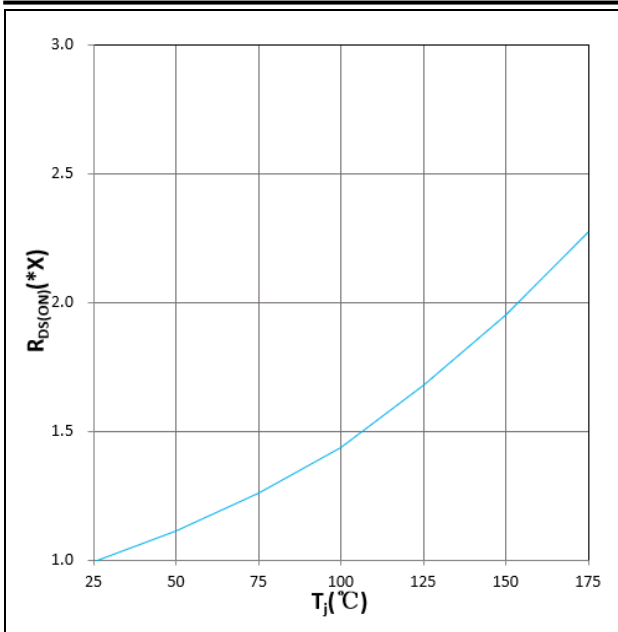


Figure 9.  $R_{DS(ON)}$  vs  $T_j$   
 $V_{GS}=+15V, I_D=600A, 1.0X=3.4m\Omega$

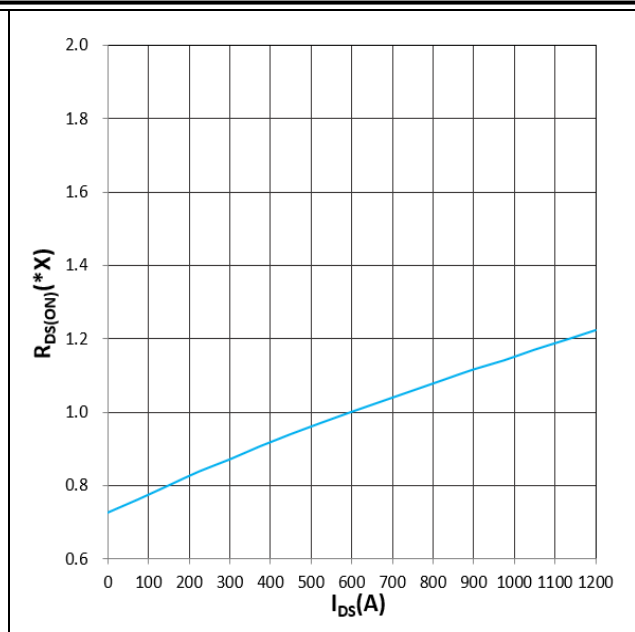


Figure 10.  $R_{DS(ON)}$  vs  $I_{DS}$   
 $T_j=25^\circ C, V_{GS}=+15V, 1.0X=3.4m\Omega$

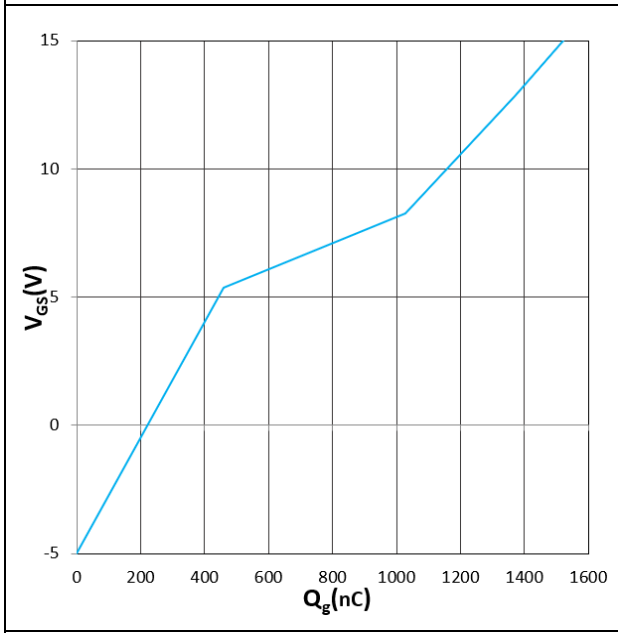


Figure 11.  $V_{GS}$  vs  $Q_g$   
 $T_j=25^\circ C, V_{DS}=1000V, I_D=450A$

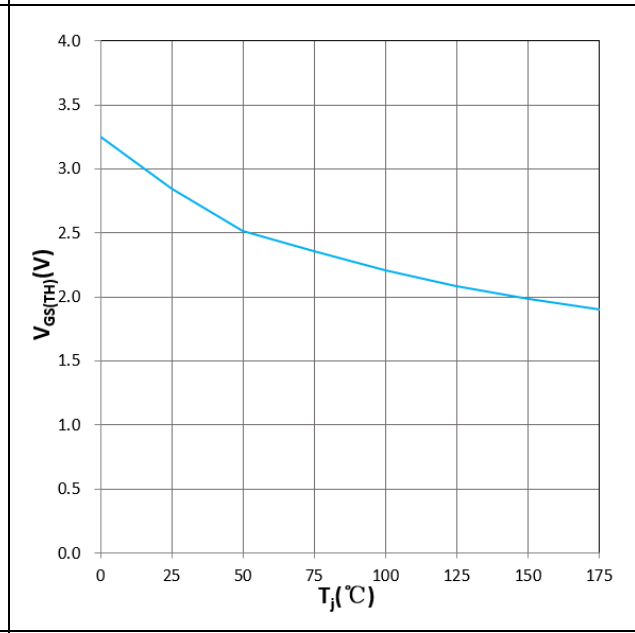


Figure 12.  $V_{GS(TH)}$  vs  $T_j$   
 $V_{GS}=V_{DS}, I_D=240mA$

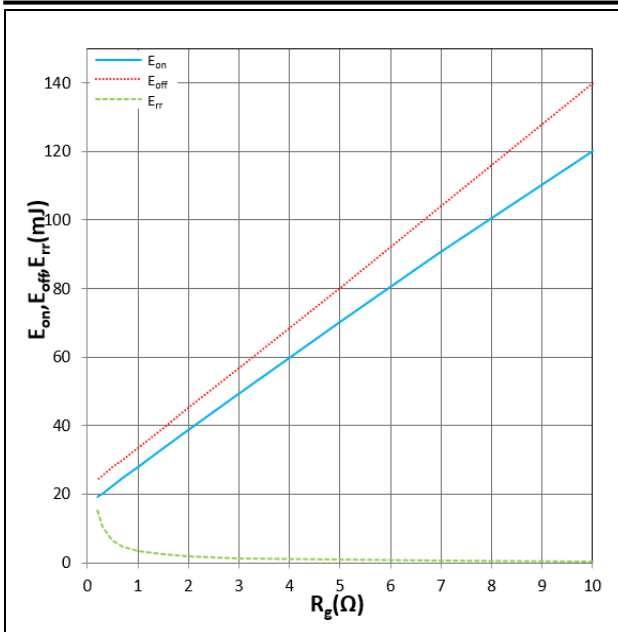


Figure 13.  $E_{on}$ ,  $E_{off}$ ,  $E_{rr}$  vs  $R_g$   
 $T_j=25^\circ\text{C}$ ,  $V_{CC}=900\text{V}$ ,  $V_{GS}=+15\text{V}/-4\text{V}$ ,  $I_D=600\text{A}$   
 Inductive Load

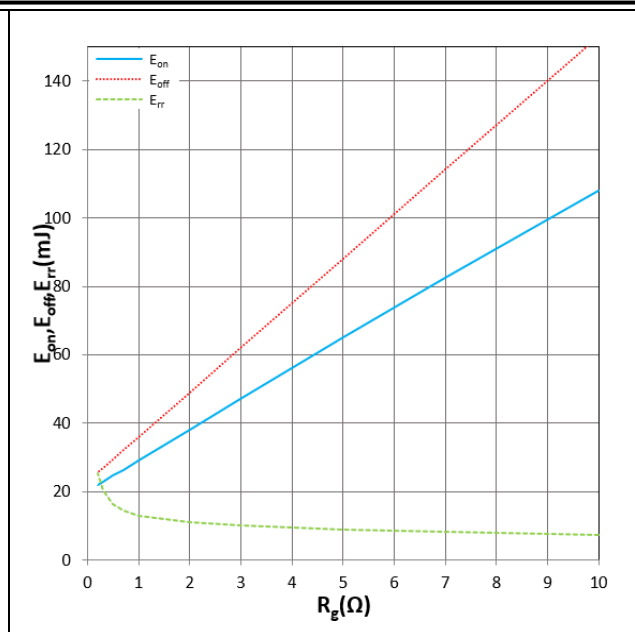


Figure 14.  $E_{on}$ ,  $E_{off}$ ,  $E_{rr}$  vs  $R_g$   
 $T_j=150^\circ\text{C}$ ,  $V_{CC}=900\text{V}$ ,  $V_{GS}=+15\text{V}/-4\text{V}$ ,  $I_D=600\text{A}$   
 Inductive Load

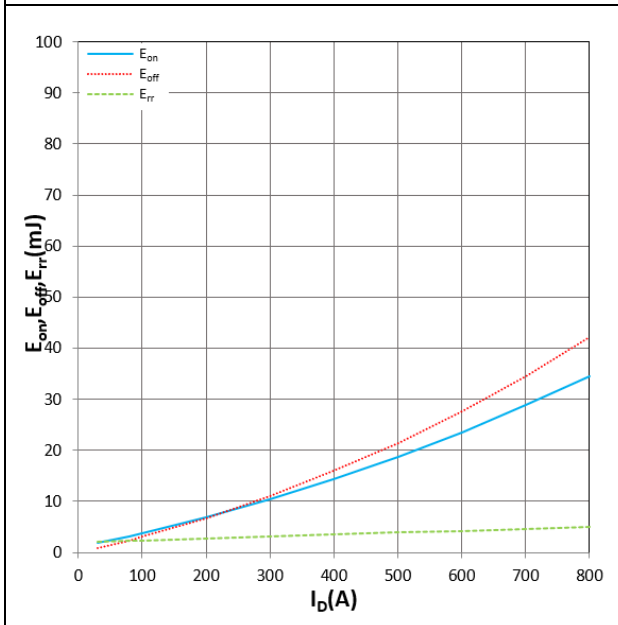


Figure 15.  $E_{on}$ ,  $E_{off}$ ,  $E_{rr}$  vs  $I_D$   
 $T_j=25^\circ\text{C}$ ,  $V_{CC}=900\text{V}$ ,  $V_{GS}=+15\text{V}/-4\text{V}$ ,  $R_g=0.5\Omega$   
 Inductive Load

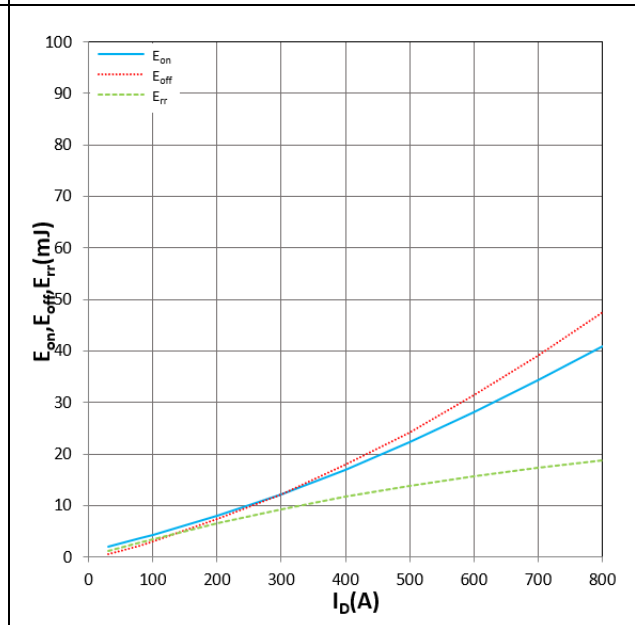


Figure 16.  $E_{on}$ ,  $E_{off}$ ,  $E_{rr}$  vs  $I_D$   
 $T_j=150^\circ\text{C}$ ,  $V_{CC}=900\text{V}$ ,  $V_{GS}=+15\text{V}/-4\text{V}$ ,  $R_g=0.5\Omega$   
 Inductive Load



### IMPORTANT NOTICE:

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